



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

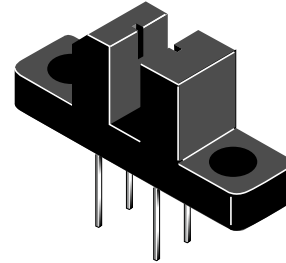
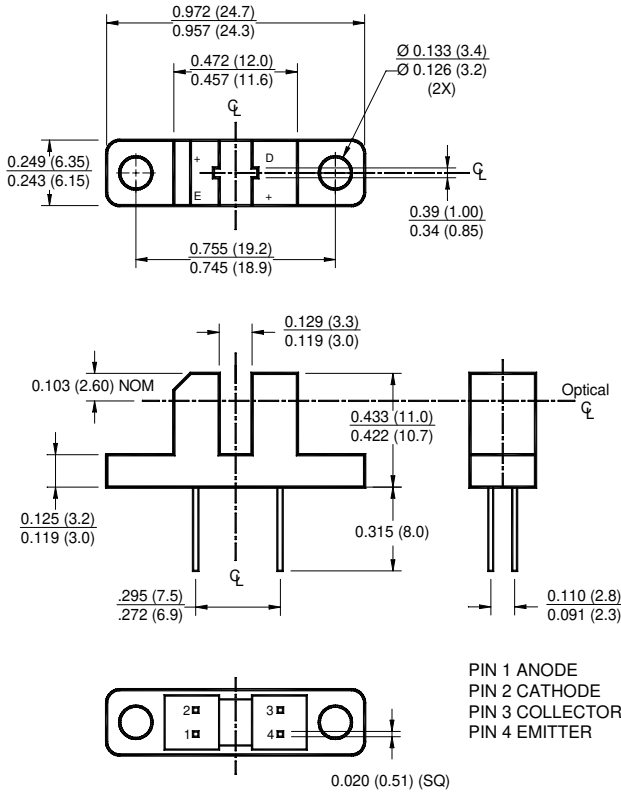
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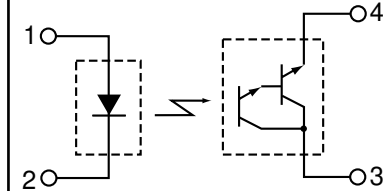
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**PACKAGE DIMENSIONS**



**SCHEMATIC**



**NOTES:**

1. Dimensions for all drawings are in inches (mm).
2. Tolerance of  $\pm .010$  (.25) on all non-nominal dimensions unless otherwise specified.

**DESCRIPTION**

The CNY29 is a gallium arsenide infrared emitting diode coupled with a silicon photo darlington in a plastic housing. The gap in the housing provides a means of interrupting the signal with tape, cards, shaft encoders, or other opaque material, switching the output from an "ON" to an "OFF" state.

**FEATURES**

- Opaque housing
- Low cost
- .035" apertures
- European "Pro Electron" registered

<b>ABSOLUTE MAXIMUM RATINGS</b> ( $T_A = 25^\circ\text{C}$ unless otherwise specified)			
Parameter	Symbol	Rating	Unit
Operating Temperature	$T_{OPR}$	-55 to +100	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55 to +100	$^\circ\text{C}$
Soldering Temperature (Iron) <sup>(2,3 and 4)</sup>	$T_{SOL-I}$	240 for 5 sec	$^\circ\text{C}$
Soldering Temperature (Flow) <sup>(2 and 3)</sup>	$T_{SOL-F}$	260 for 10 sec	$^\circ\text{C}$
<b>INPUT (EMITTER)</b>			
Continuous Forward Current	$I_F$	50	mA
Reverse Voltage	$V_R$	6	V
Power Dissipation <sup>(1)</sup>	$P_D$	100	mW
<b>OUTPUT (SENSOR)</b>			
Collector to Emitter Voltage	$V_{CEO}$	30	V
Emitter to Collector Voltage	$V_{ECO}$	6	V
Collector Current	$I_C$	40	mA
Power Dissipation ( $T_C = 25^\circ\text{C}$ ) <sup>(1)</sup>	$P_D$	150	mW

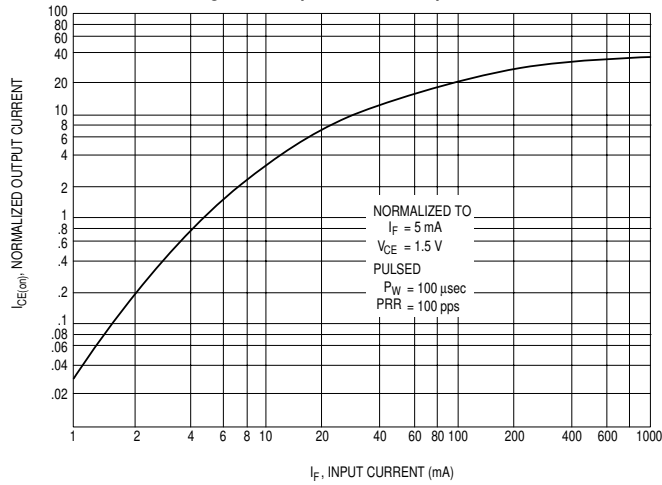
NOTE:

1. Derate power dissipation linearly 1.67 mW/ $^\circ\text{C}$  above 25 $^\circ\text{C}$ .
2. RMA flux is recommended.
3. Methanol or isopropyl alcohols are recommended as cleaning agents.
4. Soldering iron tip 1/16" (1.6mm) minimum from housing.

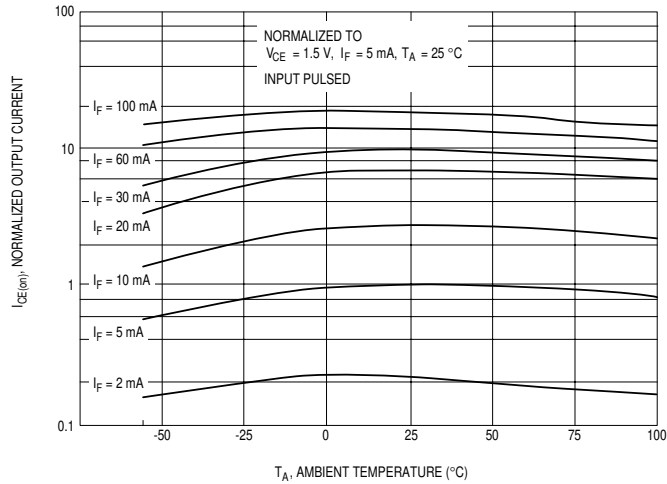
<b>ELECTRICAL / OPTICAL CHARACTERISTICS</b> ( $T_A = 25^\circ\text{C}$ )						
PARAMETER	TEST CONDITIONS	SYMBOL	MIN	TYP	MAX	UNITS
<b>INPUT (EMITTER)</b>						
Forward Voltage	$I_F = 10 \text{ mA}$	$V_F$	—	—	1.7	V
Reverse Leakage Current	$V_R = 2 \text{ V}$	$I_R$	—	—	10	$\mu\text{A}$
<b>OUTPUT (SENSOR)</b>						
Emitter to Collector Breakdown	$I_E = 100 \mu\text{A}, E_e = 0$	$BV_{ECO}$	7.0	—	—	V
Collector to Emitter Breakdown	$I_C = 10 \text{ mA}, E_e = 0$	$BV_{CEO}$	25	—	—	V
Collector to Emitter Leakage	$V_{CE} = 10 \text{ V}, E_e = 0$	$I_{CEO}$	—	—	100	nA
<b>COUPLED</b>						
On-State Collector Current	$I_F = 20 \text{ mA}, V_{CE} = 10 \text{ V}$	$I_{C(ON)}$	2.5	—	—	mA
Saturation Voltage	$I_F = 20 \text{ mA}, I_C = 0.5 \text{ mA}$	$V_{CE(SAT)}$	—	—	1.2	V
Turn-On Time	$I_F = 10 \text{ mA}, V_{CC} = 5 \text{ V}, R_L = 750\Omega$	$t_{on}$	—	150	—	$\mu\text{s}$
Turn-Off Time	$I_F = 10 \text{ mA}, V_{CC} = 5 \text{ V}, R_L = 750\Omega$	$t_{off}$	—	150	—	$\mu\text{s}$

**TYPICAL PERFORMANCE CURVES**

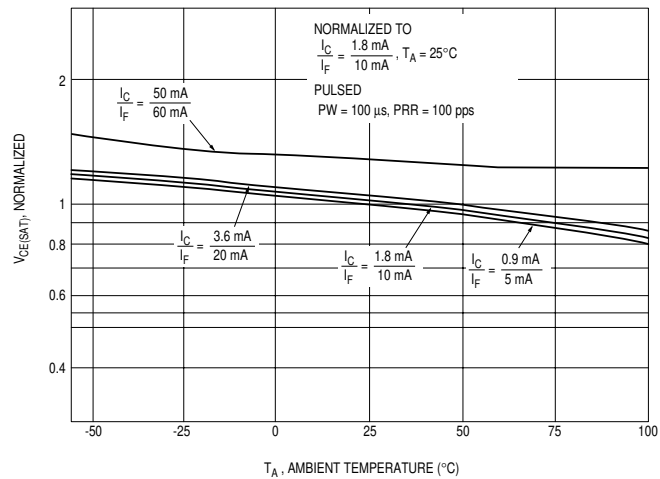
**Figure 1. Output Current vs. Input Current**



**Figure 2. Output Current vs. Temperature**

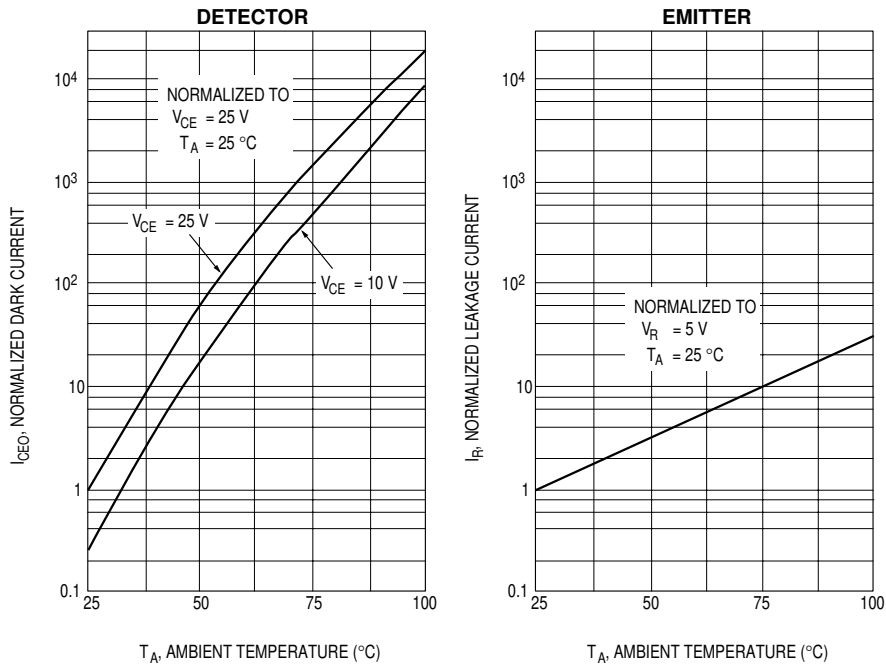


**Figure 3.  $V_{CE(SAT)}$  vs. Temperature**

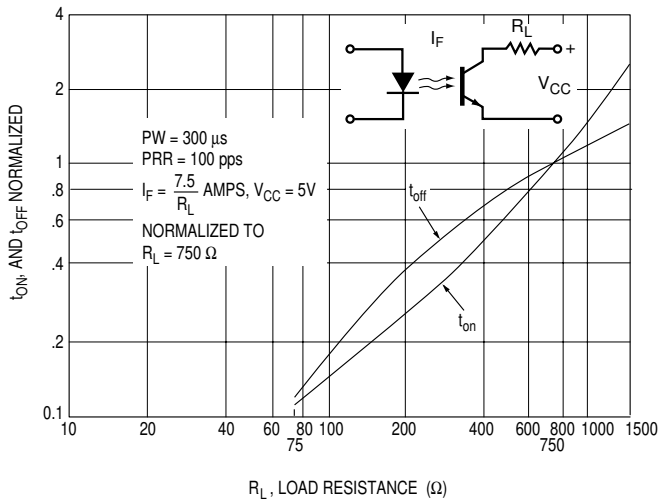


**TYPICAL PERFORMANCE CURVES (CONTINUED)**

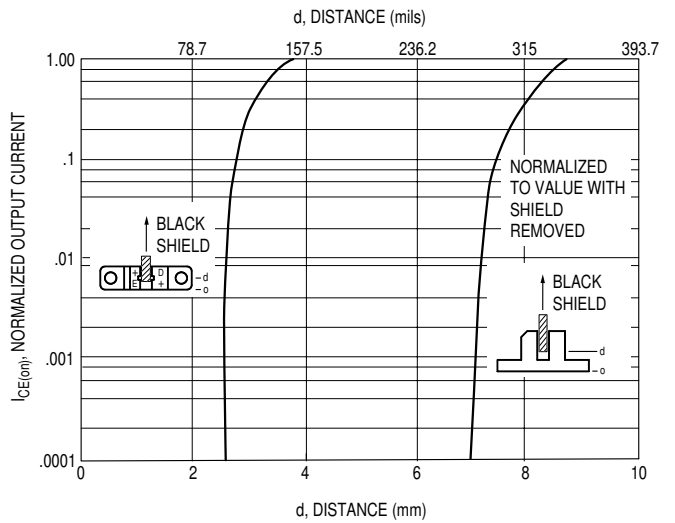
**Figure 4. Leakage Current vs. Temperature**



**Figure 5. Switching Speed vs. RL**



**Figure 6. Output Current vs. Distance**



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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.